



Product Change Notification: **BLAS-27MDGA724**

Date:

16-Jan-2025

Product Category:

16-Bit - Microcontrollers And Digital Signal Controllers, 32-Bit Microcontrollers, Analog to Digital Converters, Capacitive Touch Sensors

Notification Subject:

CCB 7203 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected dsPIC33EPxx, dsPIC33EVxx, MCP3913, MGC3030, PIC24EP12xx, PIC24EP25xx, PIC24FJ12xx, PIC24FJ64xx, PIC32MX11xx, PIC32MX12xx, PIC32MX13xx, PIC32MX15xx, PIC32MX17xx, PIC32MX21xx, PIC32MX22xx, PIC32MX23xx, PIC32MX25xx and PIC32MX27xx device families available in 28L SSOP (.209in) package at MTI assembly site.

Affected CPNs:

[BLAS-27MDGA724_Affected_CPN_01162025.pdf](#)
[BLAS-27MDGA724_Affected_CPN_01162025.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected dsPIC33EPxx, dsPIC33EVxx, MCP3913, MGC3030, PIC24EP12xx, PIC24EP25xx, PIC24FJ12xx, PIC24FJ64xx, PIC32MX11xx, PIC32MX12xx, PIC32MX13xx, PIC32MX15xx, PIC32MX17xx, PIC32MX21xx, PIC32MX22xx, PIC32MX23xx, PIC32MX25xx and PIC32MX27xx device families available in 28L SSOP (.209in) package at MTI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change

Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	
Wire Material	Au	Au CuPdAu	
Die Attach Material	3280	8390A	3280
Molding Compound Material	G600		G600
Lead-Frame Material	CDA194		CDA194
Lead-Frame Paddle Size	153 x 200 mils		153 x 200 mils
DAP Surface Prep	Ag	Bare Cu	Bare Cu

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CuPdAu as an additional bond wire material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: January 2025

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	January 2025
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Work Week	01	02	03	04	05
Initial PCN Issue Date			X		
Qual Report Availability					X
Final PCN Issue Date					X

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: January 16, 2025: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[**PCN_BLAS-27MDGA724_Qual_Plan.pdf**](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.